

February 2009

## **FDS8842NZ**

# N-Channel PowerTrench® MOSFET

**40 V, 14.9 A, 7.0 m**Ω

#### **Features**

- Max  $r_{DS(on)} = 7.0 \text{ m}\Omega$  at  $V_{GS} = 10 \text{ V}$ ,  $I_D = 14.9 \text{ A}$
- Max  $r_{DS(on)}$  = 11.6 m $\Omega$  at  $V_{GS}$  = 4.5 V,  $I_D$  = 11.6 A
- HBM ESD protection level of 4.4 kV typical(note 3)
- High performance trench technology for extremely low r<sub>DS(on)</sub> and fast switching
- High power and current handling capability
- Termination is Lead-free and RoHS Compliant

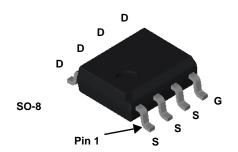
## **General Description**

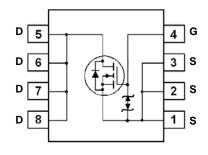
The FDS8842NZ has been designed to minimize losses in power conversion application. Advancements in both silicon and package technologies have been combined to offer the lowest  $r_{\text{DS(on)}}$  while maintaining excellent switching performance.

## **Applications**

- Synchronous Buck for Notebook Vcore and Server
- Notebook Battery
- Load Switch







## MOSFET Maximum Ratings T<sub>A</sub> = 25 °C unless otherwise noted

Symbol	Para	meter		Ratings	Units
$V_{DS}$	Drain to Source Voltage			40	V
$V_{GS}$	Gate to Source Voltage			±20	V
	Drain Current -Continuous			14.9	Δ.
'D	-Pulsed			93	_ A
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 4)	253	mJ
Б	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1a)	2.5	W
$P_{D}$	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1b)	1.0	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temper	erature Range		-55 to +150	°C

#### **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	25	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	50	*C/vv

### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS8842NZ	FDS8842NZ	SO8	13 "	12 mm	2500 units

## **Electrical Characteristics** T<sub>J</sub> = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	40			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		35		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 32 V, V <sub>GS</sub> = 0 V			1	μΑ
I <sub>GSS</sub>	Gate to Source Leakage Current	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V			±10	μΑ

#### **On Characteristics**

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.0	1.9	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		-6		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 14.9 \text{ A}$		5.6	7.0	
r <sub>DS(on)</sub>	r <sub>DS(on)</sub> Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 11.6 \text{ A}$		6.7	11.6	mΩ
		$V_{GS} = 10 \text{ V}, I_D = 14.9 \text{ A}, T_J = 125 \text{ °C}$		8.9	11.1	1
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 14.9 A		111		S

## **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 45 V V 6 V	2890	3845	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$	340	455	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1011 12	220	330	pF
R <sub>a</sub>	Gate Resistance	f = 1 MHz	0.8		Ω

#### **Switching Characteristics**

	•				
t <sub>d(on)</sub>	Turn-On Delay Time	.,	13	23	ns
t <sub>r</sub>	Rise Time	$V_{DD} = 20 \text{ V, } I_{D} = 14.9 \text{ A,}$ $V_{GS} = 10 \text{ V, } R_{GEN} = 6 \Omega$	7	14	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> = 10 V, K <sub>GEN</sub> = 6 12	34	54	ns
t <sub>f</sub>	Fall Time		5	10	ns
$Q_{g}$	Total Gate Charge	V <sub>GS</sub> = 0 V to 10 V	52	73	nC
Qg	Total Gate Charge	$V_{GS} = 0 \text{ V to 5 V}$ $I_{D} = 20 \text{ V},$ $I_{D} = 14.9 \text{ A}$	27	38	nC
Q <sub>gs</sub>	Gate to Source Charge	1 <sub>D</sub> = 14.9 A	8.6		nC
$Q_{gd}$	Gate to Drain "Miller" Charge		9.7		nC

#### **Drain-Source Diode Characteristics**

V <sub>SD</sub> Source to Drain Diode Forward Voltage	Source to Drain Diode, Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 14.9 A	0.8	1.2	V
	$V_{GS} = 0 V, I_{S} = 2.1 A$	0.7	1.2	V	
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = 14.9 A, di/dt = 100 A/μs	26	42	ns
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>F</sub> = 14.9 A, α/αι = 100 A/μs	15	27	nC

<sup>1.</sup> R<sub>BJA</sub> is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>BJC</sub> is guaranteed by design while R<sub>BCA</sub> is determined by the user's board design.



a) 50 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper.



b) 125 °C/W when mounted on a minimum pad.

- 2. Pulse Test: Pulse Width < 300  $\mu$ s, Duty cycle < 2.0%. 3. The diode connected between the gate and source servers only as protection against ESD. No gate overvoltage rating is implied. 4. Starting T $_J$  = 25 °C, L = 3 mH, I $_{AS}$  = 13 A, V $_{DD}$  = 40 V, V $_{GS}$  = 10 V.

## Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

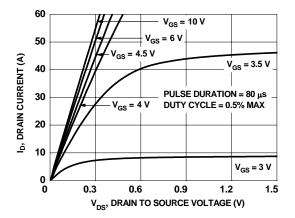


Figure 1. On-Region Characteristics

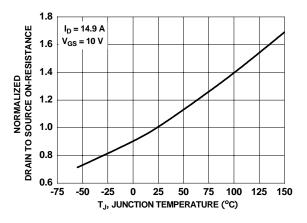


Figure 3. Normalized On-Resistance vs Junction Temperature

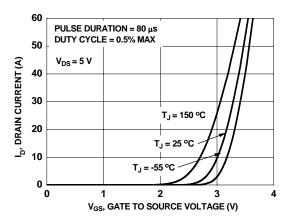


Figure 5. Transfer Characteristics

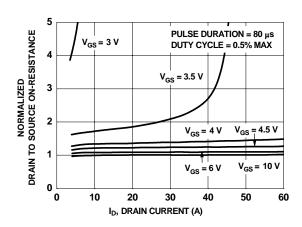


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

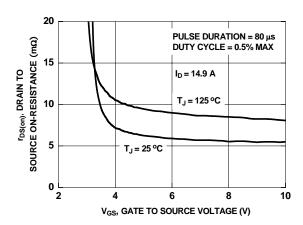


Figure 4. On-Resistance vs Gate to Source Voltage

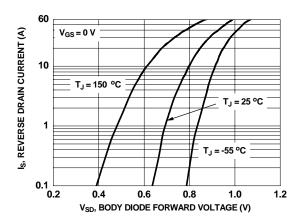


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

## Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

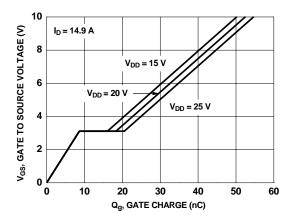


Figure 7. Gate Charge Characteristics

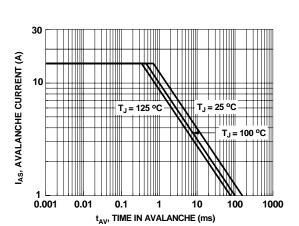


Figure 9. Unclamped Inductive Switching Capability

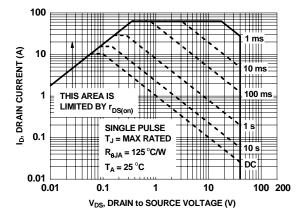


Figure 11. Forward Bias Safe Operating Area

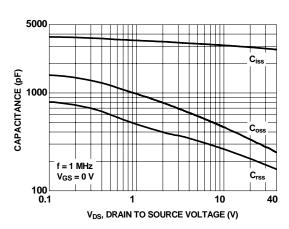


Figure 8. Capacitance vs Drain to Source Voltage

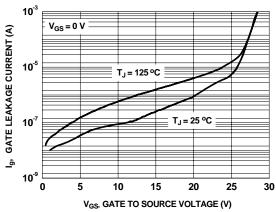


Figure 10. Igss vs Vgs

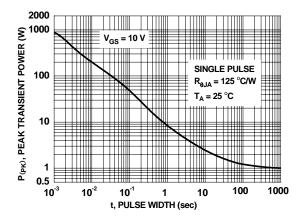


Figure 12. Single Pulse Maximum Power Dissipation

## **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

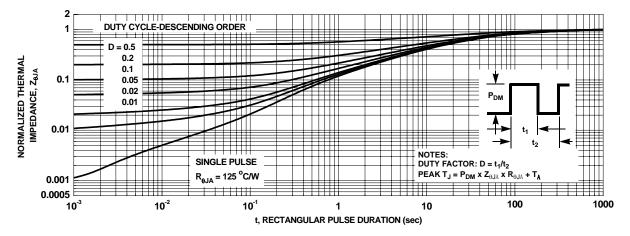


Figure 13. Transient Thermal Response Curve





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